



Opening Ceremony of Molded Interconnect Devices Committee of FSZI The First China-Europe 3D-MID Technology Exchange Conference

Thanks to the support from all the partners and friends, we are now glad to announce the establishment of the Molded Interconnect Devices Committee of FSZI, the first 3D- MID Association in China. On 25th -26th, Sep.2013 the opening ceremony of the Committee will be held at the Four Points Sheraton Hotel Suzhou, China. Also, thanks to the cooperation of the German Research Association of Molded Interconnect Devices - 3-D MID e.V., the 1st China-Europe MID Technology Exchange Conference will be held at the same time.

On the MID Conference, the professional speeches will be given involving all aspects of MID industry: Such as plastic/material, chemical process, 3D assembly, as well as the newest applications and industry trends, etc. At the same time a MID tradeshow will be held during the conference. Your participation is cordially expected.

We look forward to seeing you!

Prof. Yewen Zhang
Director of Committee
Molded Interconnect Devices Committee of FSZI

2013.9.25 - 26
Four Points Sheraton Hotel
Suzhou • China

Initiators



Program

Opening Ceremony of Molded Interconnect Devices Committee of FSZI The First China-Europe MID Technology Exchange Conference

Four Points Sheraton Hotel • No. 8 Moon Bay Road • Suzhou Industrial Park • Suzhou

24th Sep.

16:00 - 19:00 Registration

25th Sep.

08:30 - 09:30 Final Registration

10:00 - 10:45 Opening Ceremony

Speakers: Chairman of FSZI; Chairman of the Research Association 3-D MID e.V
Director of MID Committee China

Coffee break

11:00 - 12:15 MID Applications

Speakers: Harting Mitronics Swiss; Molex; Sabic-Auto

Lunch

13:30 - 15:00 MID Materials and 3D Assembly

Speakers: SABIC; Evonik; Haecker; HSG-IMAT

Coffee break

15:30 - 17:00 New Progress of MID Technology

Speakers: LPKF; Macdermid; Ticona; XEON

18:00 Dinner and Free Communication

26th Sep.

09:30 - 10:45 MID Market Trends

Speakers: MEP; Enthone; Essemtech

Coffee break

11:00 - 12:30 MID Applications

Speakers: Viscom; Cicor Swiss; HSG-IMAT; Lasermicronics

Please return this Reply Slip by
email to : info@3dmid.cn

Deadline: 2013.8.15

Reply on Committee Entrance

Please fill in below form when your company hopes to become a member of MID Committee.

COMPANY	ADDRESS	CONTACT PERSON	APPLICATION TO BE ACTIVE MEMBER OR NOT

1. Annual membership fee (12 months from the enrolment date):
Ordinary Member, RMB 6,000/year; Active Member, RMB 20,000/year
2. Members of MID Committee will benefit themselves on industrial and technical information sharing and exchange, as well as opportunities in participation of various Committee activities. Additionally, MID member is automatically an ordinary member of FSZI, enjoying the routine services of FSZI.
3. Active members will take part into MID Committee execution works, and enjoy preferential prices and rights in Committee activities.

Reply on MID Conference Participation

COMPANY	NAME	POSITION	HANDY	EMAIL

Conference fee: RMB 600/person, including expenses of conference, coffee break, lunch, and dinner, excluding travel and accommodation expenses.

1. Non-member of MID Committee can apply to participate MID Conference with bearing conference fees.
2. Ordinary member enjoys 2 free admission for conference. Participants beyond need to bear conference fees.
3. Active member enjoys 3 free admission for conference. Participants beyond need to bear conference fees.

Reply on Tradeshow Participation

Please fill in below form when your company hopes to participate the tradeshow during MID conference.
(only for MID Committee members)

COMPANY	TRADE SHOW PARTICIPATION OR NOT

Tradeshow fee: Ordinary Member, RMB 3,000; Active Member, RMB 2,000

Due to condition limits, no power supply for large equipment provided.